

Meeting with Prime Minister of Japan at Osaka

2890. DR. T. SUBBARAMI REDDY:

SHRIMATI AMBIKA SONI:

Will the Minister of EXTERNAL AFFAIRS be pleased to state:

(a) the issues discussed between the Prime Minister of Japan and the Indian Prime Minister recently at Osaka;

(b) the main topics highlighted by Japan with regard to G-20 meeting;

(c) the details of response of Indian Government thereto; and

(d) whether any trilateral meeting between India, US and Japan was held and if so, the details thereof?

THE MINISTER OF STATE IN THE MINISTRY OF EXTERNAL AFFAIRS (SHRI V. MURALEEDHARAN): (a) Prime Minister met Japanese PM Shinzo Abe on 27 June, 2019 on the margins of G20 Summit, Osaka. The two leaders reviewed developments in India-Japan Special Strategic and Global Partnership since the last Annual Summit in October, 2018 and expressed satisfaction over the steady progress achieved in bilateral relations in recent years. They also discussed the ongoing economic-cooperation between India and Japan, and new areas of India-Japan partnership such as digital cooperation, disaster management, etc. They also discussed global issues of mutual interest. The two Prime Ministers also took note of the important upcoming engagements between the two countries in 2019, including the next India-Japan Annual Summit.

(b) and (c) Japan, as the current President of G20, highlighted the following areas at the G20 Summit, Osaka: Development of Quality Infrastructure; Digital Economy and Society 5.0; Free Trade and Economic Growth; Women Empowerment; Global Health and Ageing; Climate change and Energy; and Marine Plastic Waste. India welcomed the priority areas highlighted by Japan and would continue to work with G20 partners on these issues.

(d) A trilateral Summit meeting was held between India, US and Japan on 28 June, 2019 on the margins of G20 Summit, Osaka, in which the three leaders discussed regional and international issues of mutual interest.

Passports with advanced security features

2891. SHRI K. R. ARJUNAN: Will the Minister of EXTERNAL AFFAIRS be pleased to state:

(a) whether it is a fact that Government is considering to come out with passports with advanced security features;

(b) whether it is also a fact that chips would be installed in the booklets; and

(c) if so, the details thereof?

THE MINISTER OF STATE IN THE MINISTRY OF EXTERNAL AFFAIRS (SHRI V. MURALEEDHARAN): (a) to (c) Yes. The Ministry has plans to issue chip enabled e-passports to citizens with advanced security features. The personal particulars of the applicants would be digitally signed and stored in the chip which would be embedded in the physical passport booklet. In case anyone tampers with the chip, the system shall be able to identify it resulting in the failure of the passport authentication.

The Government has given its approval for procurement of electronic contactless inlays for manufacturing of e-passports to India Security Press (ISP) Nasik. In this regard, ISP, Nasik, has been authorized to float a Global three-stage tender for procurement of International Civil Aviation Organisation (ICAO)-compliant electronic contactless inlays along with its operating system, which is required for manufacture of e-passports. Manufacture of e-passport will commence on the successful completion of the tendering and procurement process by ISP, Nasik.

Integration of diplomatic missions with Passport Seva Project

2892. SHRI K. R. ARJUNAN: Will the Minister of EXTERNAL AFFAIRS be pleased to state:

(a) whether it is a fact that Government is on its way to integrate all the diplomatic missions and posts with the Passport Seva Project;

(b) if so, the details thereof;

(c) whether at present there are 505 Passport Seva Kendras out of which 412 are Post Office Passport Seva Kendras; and

(d) if so, the details thereof?

THE MINISTER OF STATE IN THE MINISTRY OF EXTERNAL AFFAIRS (SHRI V. MURALEEDHARAN): (a) and (b) The Ministry is in the process of linking and integrating all the Missions and Posts abroad with the Passport Seva Project (PSP). As on 13 July, 2019, the Ministry has integrated the passport issuance systems in 29 Missions and Posts in Australia, Bahrain, Canada, China, Kuwait, Malaysia, Oman, Qatar, Saudi Arabia, Singapore, Sri Lanka, Thailand, United Arab Emirates,